

MARKED UP VERSION OF CLAIMS

4. (Amended) A printed wiring board comprising an internal insulating substrate having a conductor circuit formed on a surface thereof, [at least one] an internal insulating layer laminated on the surface of the internal insulating substrate, and an external insulating layer laminated on a surface of the internal insulating layer, the internal insulating layer and the external insulating layer having an internal conductor circuit and an external conductor circuit respectively;

wherein the internal insulating layer [is of a glass cloth-reinforced prepreg; and the external insulating layer is of a resin] comprises two or more internal insulating layers.

7. (Amended) A method of manufacturing a printed wiring board having a plurality of conductive layers which are built up via insulating layers respectively and are electrically connected to one another via interconnecting through holes, the method comprising the steps of:

forming conductive layers on a plurality of insulating layers respectively;

laminating and press-bonding the resulting insulating layers to form a multilayer substrate;

irradiating a laser beam on the multilayer substrate at interconnecting through hole-forming portions to define interconnecting through holes such that bottoms of the through holes reach the conductive layers;

covering the walls of the interconnecting through holes with metal plating films; and

fusing solder balls against the interconnecting through holes and filling them with solder.

10. (Amended) The method of manufacturing a printed wiring board according to [any of claims] claim 7 [to 9], wherein the insulating layers are flexible films made of a glass fiber-reinforced resin.

11. (Amended) A printed wiring board comprising an interconnecting through hole penetrating an insulating substrate, a covering pad covering one opening of the interconnecting through hole, and a conductor circuit provided along a peripheral edge of the other opening which remains open;

wherein the covering pad and the conductor circuit are electrically connected to each other via a metal plating film covering a wall of the interconnecting through hole; and a solder ball for external connection is located onto the surface of the covering pad at a position offset from the interconnecting through hole.

14. (Amended) The printed wiring board according to [any one of claims] claim 11 [to 13], wherein the surface of the insulating substrate is covered with a solder resist and the

interconnecting through hole is filled with the solder resist.

15. (Amended) A printed wiring board comprising an interconnecting through hole penetrating an insulating substrate, an annular pad disposed along a peripheral edge of one opening of the interconnecting through hole so as not to cover the opening, a covering pad covering the other opening of the interconnecting through hole and a conductor circuit connected to the covering pad;

wherein the annular pad and the covering pad are electrically connected to each other by a metal plating film covering a wall of the interconnecting through hole; and a solder ball for external connection is located onto the surface of the annular pad at a position offset from the interconnecting through hole.

18. (Amended) The printed wiring board according to [any one of claims] claim 15 [to 17], wherein the surface of the insulating substrate is covered with a solder resist.